

**Features**

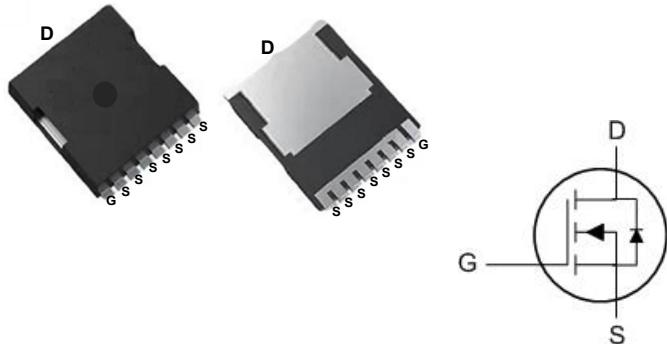
- Split Gate Trench MOSFET technology
- Excellent package for heat dissipation
- High density cell design for low  $R_{DS(ON)}$

**Product Summary**

BVDSS	RDS(on)	ID
60V	1.25mΩ	400A

**Applications**

- DC-DC Converters
- Power management functions
- Synchronous-rectification applications

**TOLL-8L Pin Configuration****Absolute Maximum Ratings (TA = 25°C, unless otherwise noted)**

Parameter		Symbol	Value	Unit
Drain-Source Voltage		$V_{DS}$	60	V
Gate-Source Voltage		$V_{GS}$	$\pm 20$	V
Continuous Drain Current	$T_c=25^\circ C$	$I_D$	400	A
	$T_c=100^\circ C$		268	
Pulsed Drain Current <sup>1</sup>		$I_{DM}$	1512	A
Single Pulse Avalanche Energy <sup>2</sup>		$E_{AS}$	500	mJ
Total Power Dissipation	$T_c=25^\circ C$	$P_D$	454.5	W
Operating Junction and Storage Temperature Range		$T_J, T_{STG}$	-55 to 175	°C

**Thermal Characteristics**

Parameter		Symbol	Value	Unit
Thermal Resistance from Junction-to-Ambient <sup>3</sup>		$R_{\theta JA}$	39	°C/W
Thermal Resistance from Junction-to-Case		$R_{\theta JC}$	0.33	°C/W

## N-Ch 60V Fast Switching MOSFETs

Electrical Characteristics ( $T_J = 25^\circ\text{C}$ , unless otherwise noted)

Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
<b>Static Characteristics</b>						
Drain-Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{GS} = 0\text{V}, I_D = 250\mu\text{A}$	60	-	-	V
Gate-body Leakage current	$I_{GSS}$	$V_{DS} = 0\text{V}, V_{GS} = \pm 20\text{V}$	-	-	$\pm 100$	nA
Zero Gate Voltage Drain Current $T_J=25^\circ\text{C}$	$I_{DSS}$	$V_{DS} = 60\text{V}, V_{GS} = 0\text{V}$	-	-	1	$\mu\text{A}$
$T_J=100^\circ\text{C}$			-	-	100	
Gate-Threshold Voltage	$V_{GS(\text{th})}$	$V_{DS} = V_{GS}, I_D = 250\mu\text{A}$	2	2.9	4	V
Drain-Source on-Resistance <sup>4</sup>	$R_{DS(\text{on})}$	$V_{GS} = 10\text{V}, I_D = 20\text{A}$	-	1.25	1.55	$\text{m}\Omega$
Forward Transconductance <sup>4</sup>	$g_{fs}$	$V_{DS}=10\text{V}, I_D=20\text{A}$	-	62	-	S
<b>Dynamic Characteristics<sup>5</sup></b>						
Input Capacitance	$C_{iss}$	$V_{DS} = 30\text{V}, V_{GS} = 0\text{V}, f = 1\text{MHz}$	-	5990	-	pF
Output Capacitance	$C_{oss}$		-	2257	-	
Reverse Transfer Capacitance	$C_{rss}$		-	86	-	
Gate Resistance	$R_g$	$f = 1\text{MHz}$	-	2.6	-	$\Omega$
<b>Switching Characteristics<sup>5</sup></b>						
Total Gate Charge	$Q_g$	$V_{GS} = 10\text{V}, V_{DS} = 30\text{V}, I_D = 20\text{A}$	-	102	-	nC
Gate-Source Charge	$Q_{gs}$		-	24.6	-	
Gate-Drain Charge	$Q_{gd}$		-	28.2	-	
Turn-on Delay Time	$t_{d(on)}$	$V_{GS} = 10\text{V}, V_{DD} = 30\text{V}, R_G = 3\Omega, I_D = 20\text{A}$	-	15.6	-	ns
Rise Time	$t_r$		-	29	-	
Turn-off Delay Time	$t_{d(off)}$		-	63	-	
Fall Time	$t_f$		-	51	-	
Body Diode Reverse Recovery Time	$t_{rr}$	$I_F = 20\text{A}, dI/dt = 100\text{A}/\mu\text{s}$	-	80	-	ns
Body Diode Reverse Recovery Charge	$Q_{rr}$		-	114	-	nC
<b>Drain-Source Body Diode Characteristics</b>						
Diode Forward Voltage <sup>4</sup>	$V_{SD}$	$I_S = 20\text{A}, V_{GS} = 0\text{V}$	-	-	1.2	V
Continuous Source Current	$T_c=25^\circ\text{C}$	$I_S$	-	-	400	A

Notes:

1. Repetitive rating, pulse width limited by junction temperature  $T_{J(\text{MAX})}=175^\circ\text{C}$ .
2. The test condition is  $V_{DD} = 90\text{V}, V_{GS} = 10\text{V}, L = 0.4\text{mH}, I_{AS} = 50\text{A}$ .
3. The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper, The value in any given application depends on the user's specific board design.
4. The data tested by pulsed, pulse width  $\leq 300\mu\text{s}$ , duty cycle  $\leq 2\%$ .
5. This value is guaranteed by design hence it is not included in the production test.

## Typical Characteristics

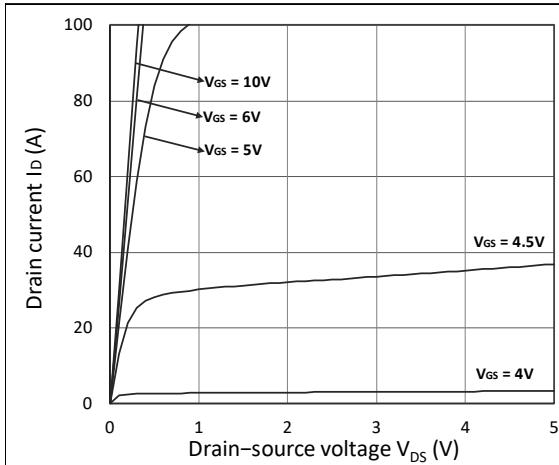


Figure 1. Output Characteristics

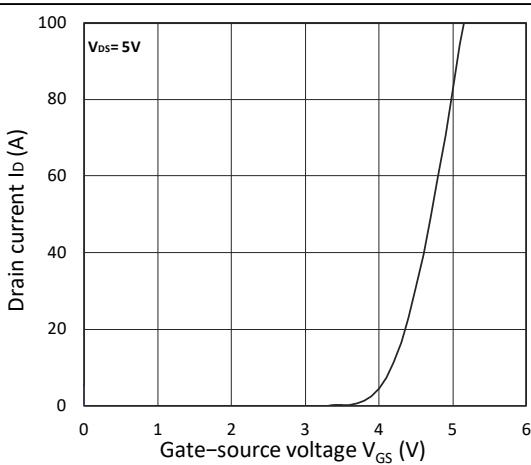


Figure 2. Transfer Characteristics

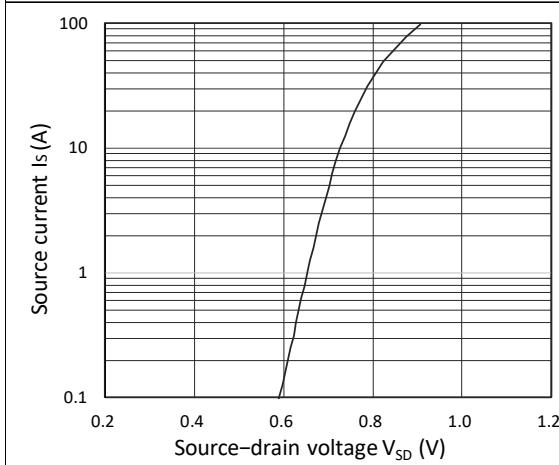


Figure 3. Forward Characteristics of Reverse

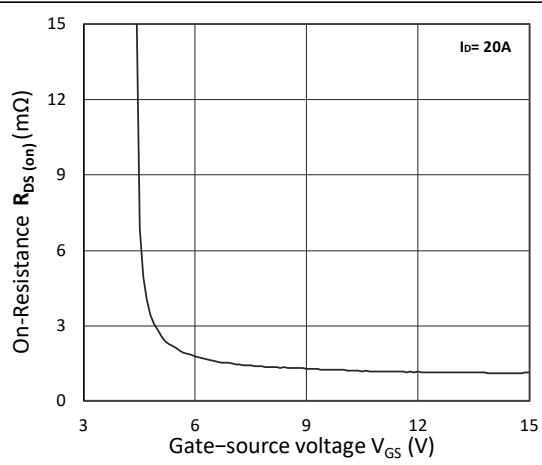


Figure 4.  $R_{DS(on)}$  vs.  $V_{GS}$

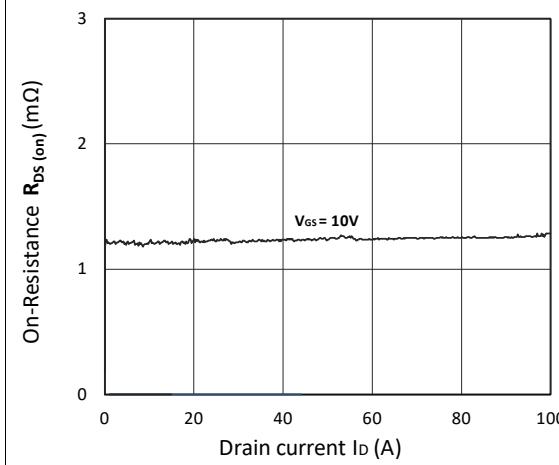


Figure 5.  $R_{DS(on)}$  vs.  $I_D$

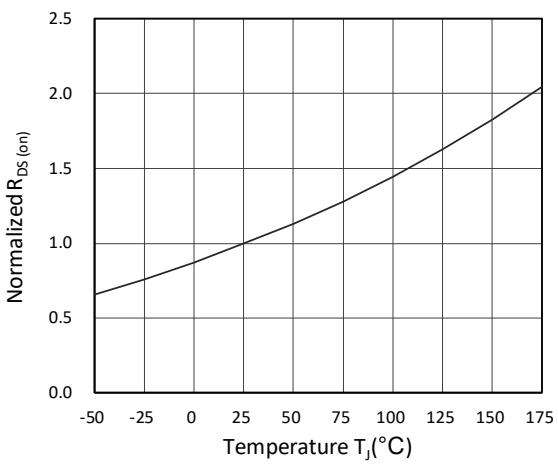


Figure 6. Normalized  $R_{DS(on)}$  vs. Temperature

## N-Ch 60V Fast Switching MOSFETs

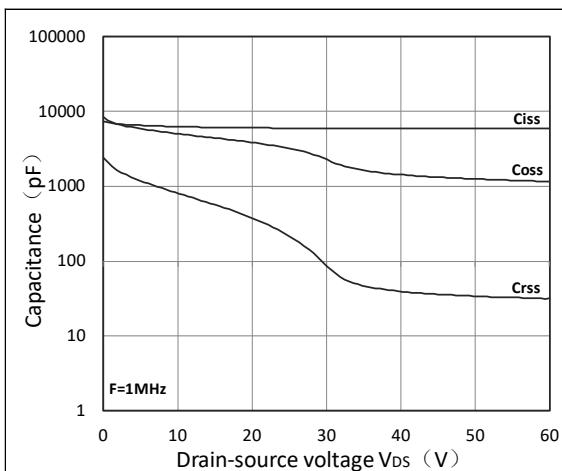


Figure 7. Capacitance Characteristics

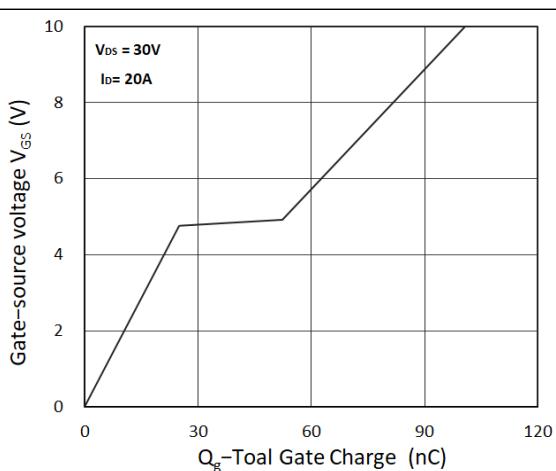


Figure 8. Gate Charge Characteristics

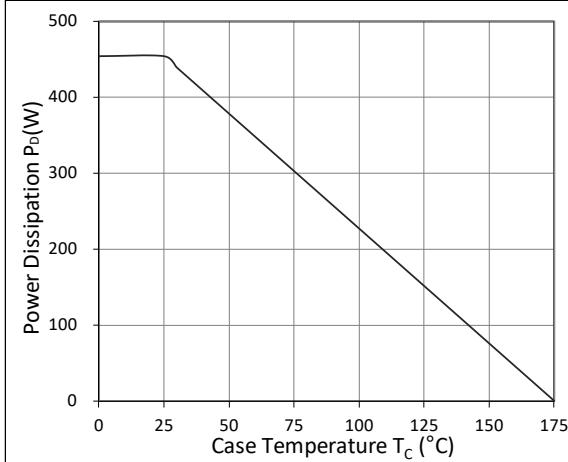


Figure 9. Power Dissipation

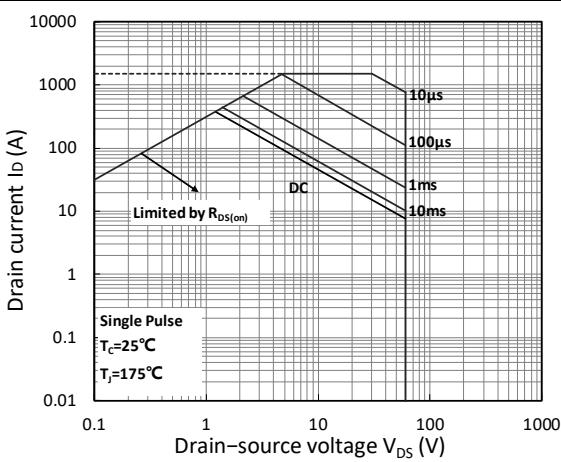


Figure 10. Safe Operating Area

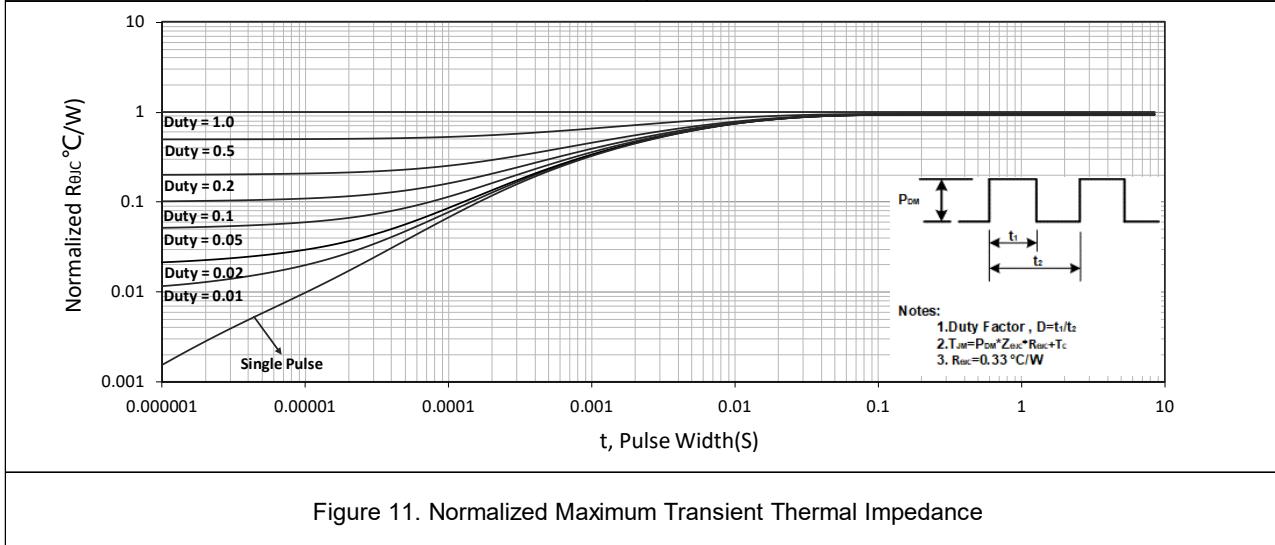


Figure 11. Normalized Maximum Transient Thermal Impedance

## Test Circuit

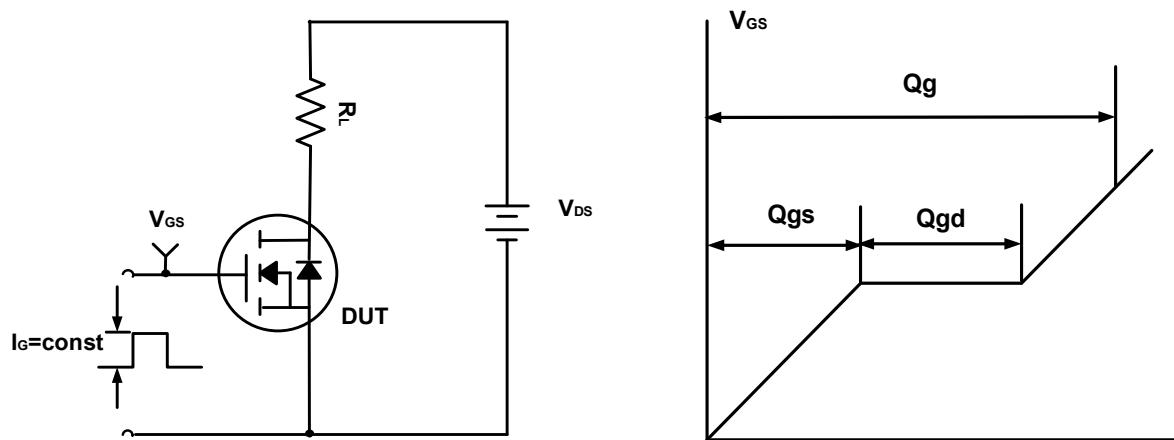


Figure A. Gate Charge Test Circuit &amp; Waveforms

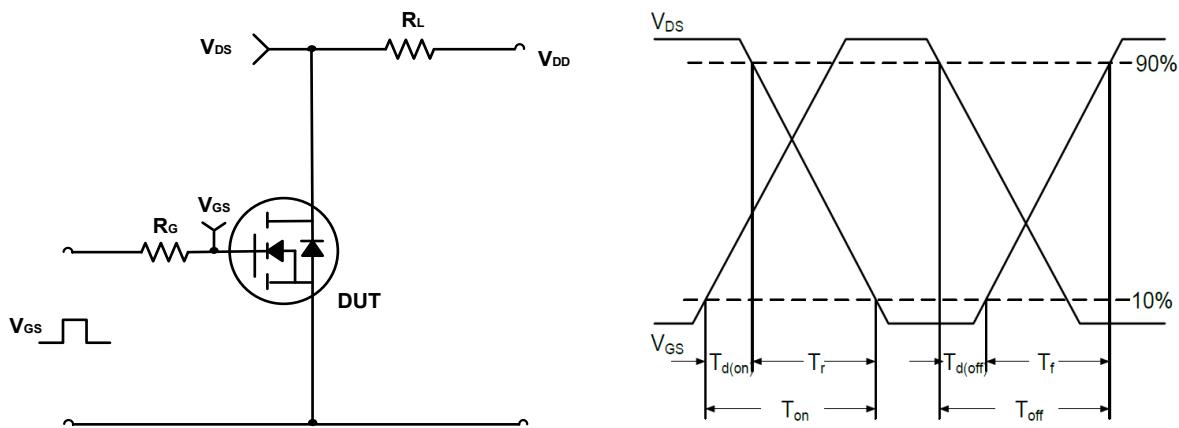


Figure B. Switching Test Circuit &amp; Waveforms

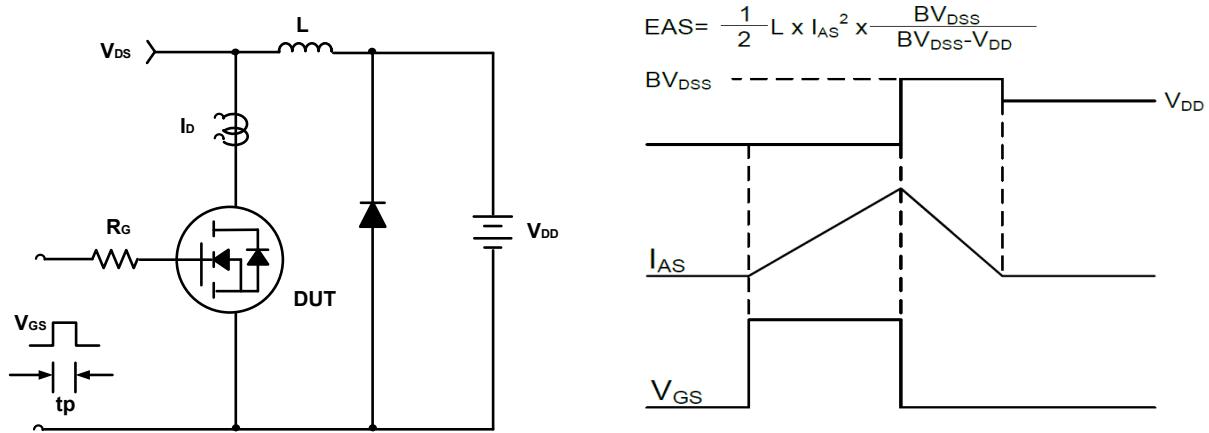
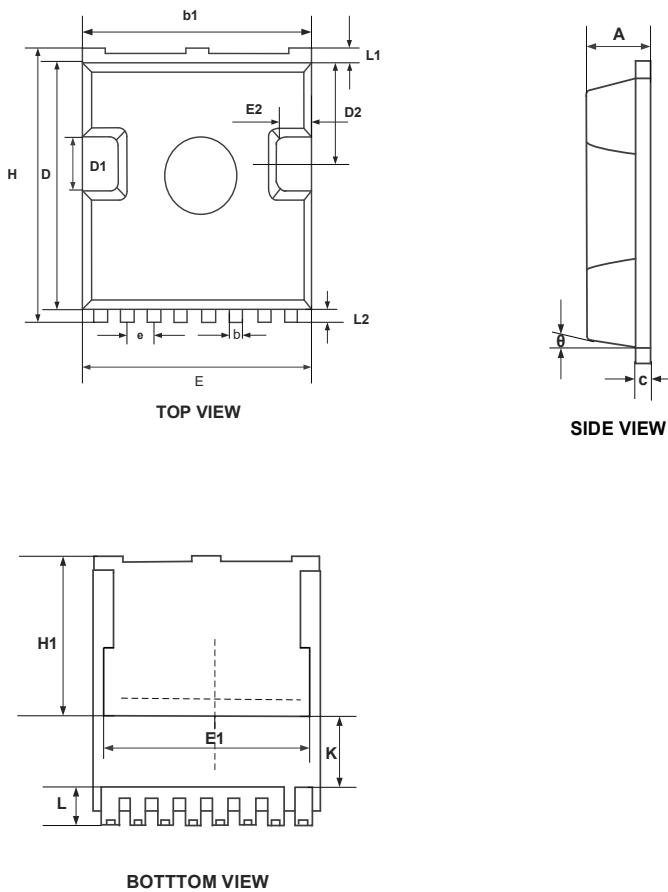


Figure C. Unclamped Inductive Switching Circuit &amp; Waveforms

## N-Ch 60V Fast Switching MOSFETs

## Mechanical Dimensions for TOLL-8L



## COMMON DIMENSIONS

SYMBOL	MM	
	MIN	MAX
A	2.20	2.40
b	0.60	0.90
b1	9.70	9.90
c	0.40	0.60
D	10.20	10.60
D1	3.10	3.50
D2	4.45	4.75
E	9.70	10.10
E1	7.80BSC	
E2	0.50	0.70
e	1.200 BSC	
H	11.45	11.90
H1	6.75 BSC	
K	3.10 REF	
L	1.70	2.10
L1	0.60	0.80
L2	0.50	0.70
$\theta$	10° REF	